

Taiwan Semiconductor

Glass Passivated Bridge Rectifiers

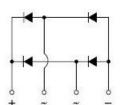
FEATURES

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC





KBL





MECHANICAL DATA

Case: KBL

Molding compound, UL flammability classification rating 94V-0 **Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test **Polarity:** Polarity as marked on the body

Weight: 5.6 g (approximately)

PARAMETER	SYMBOL	KBL	KBL	KBL	KBL	KBL	KBL	KBL	Unit
		601G	602G	603G	604G	605G	606G	607G	Onit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	6			Α				
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	175				А			
Rating for fusing (t<8.3ms)	l ² t	127			A ² s				
Maximum instantaneous forward voltage (Note 1) $\rm I_{F}{=}~3~A$ $\rm I_{F}{=}~6~A$	V _F	1.0 1.1			٧				
Maximum DC reverse current $T_J=25~^{\circ}\text{C}$ at rated DC blocking voltage $T_J=125~^{\circ}\text{C}$	I _R	10 500			μA				
Typical thermal resistance	R _{θJL} R _{θJA}	7.5 13			°C/W				
Operating junction temperature range	TJ	- 55 to +150		оС					
Storage temperature range	T _{STG}			-	55 to +15	50			°С

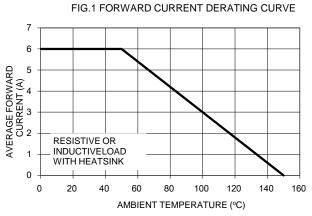
Note 1: Pulse Test with PW=300µs,1% Duty Cycle

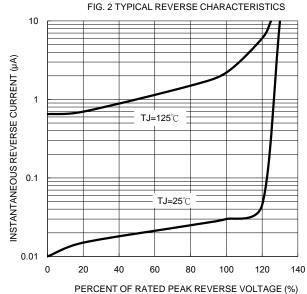


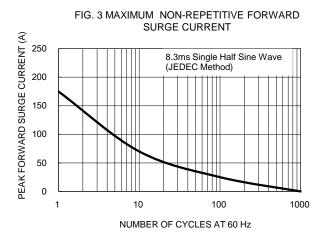
ORDERING INFORMATION						
ORDERING CODE	PACKAGE	PACKING				
KBL601G T0	KBL	500 / Trays				
KBL602G T0	KBL	500 / Trays				
KBL603G T0	KBL	500 / Trays				
KBL604G T0	KBL	500 / Trays				
KBL605G T0	KBL	500 / Trays				
KBL606G T0	KBL	500 / Trays				
KBL607G T0	KBL	500 / Trays				

RATINGS AND CHARACTERISTICS CURVES

(TA=25°C unless otherwise noted)







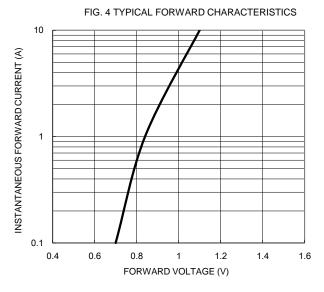
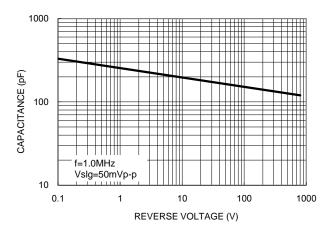
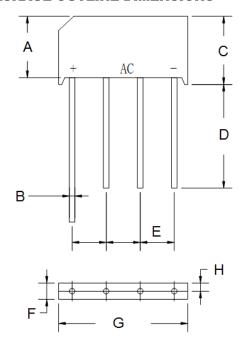




FIG. 5 TYPICAL JUNCTION CAPACITANCE



PACKAGE OUTLINE DIMENSIONS



DIM.	Unit	(mm)	Unit (inch)		
DIN.	Min	Max	Min	Max	
Α	13.70	14.70	0.539	0.579	
В	1.20	1.30	0.047	0.051	
С	15.20	16.30	0.598	0.642	
D	19.00	-	0.748	-	
Е	4.60	5.60	0.181	0.220	
F	5.50	6.50	0.217	0.256	
G	18.50	19.50	0.728	0.768	
Н	2.1 (TYP)		0.083 (TYP)		

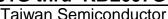
MARKING DIAGRAM



P/N = Specific Device Code

YWW = Date Code

F = Factory Code





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